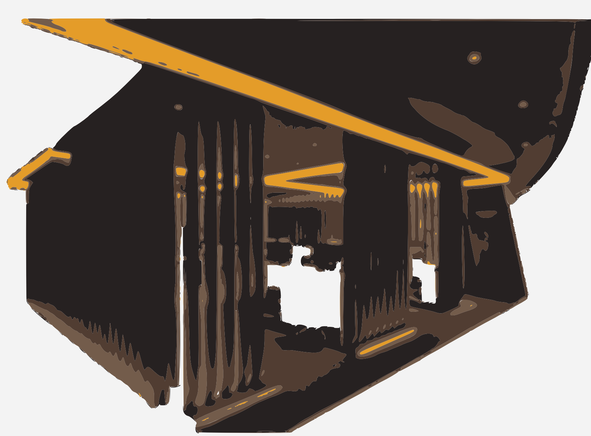
Gentech

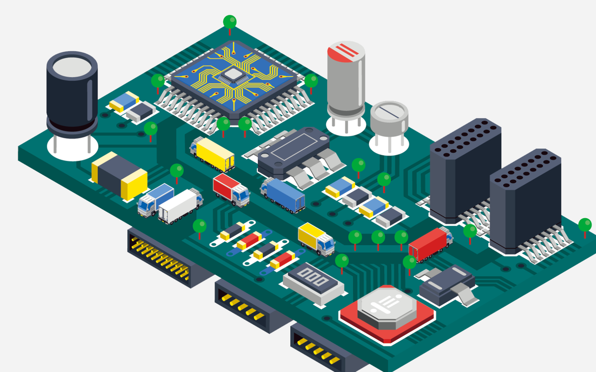
ASSEMBLING INNOVATION

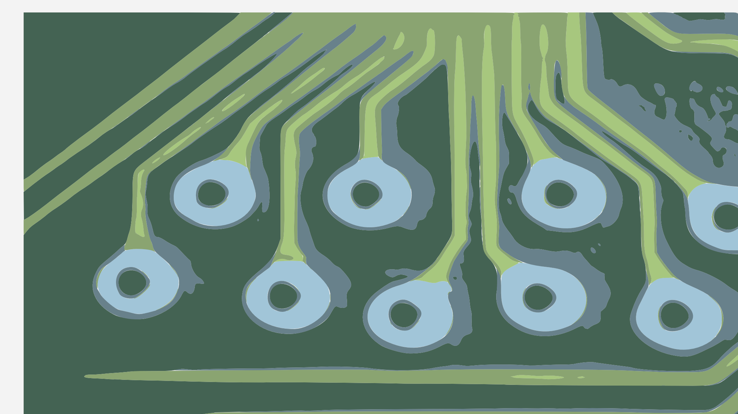
GT-0012020



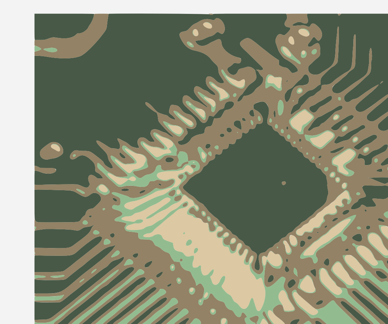
R&D and NPI Centre
Shatin, Hong Kong

Assembly Plant
Dongguan, China

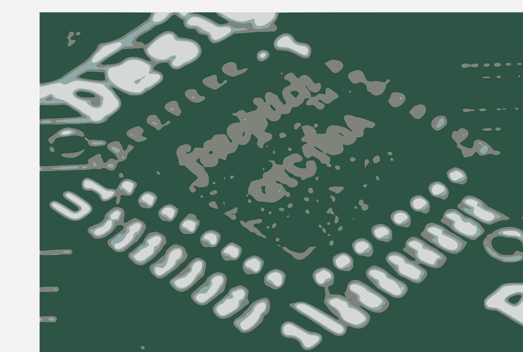




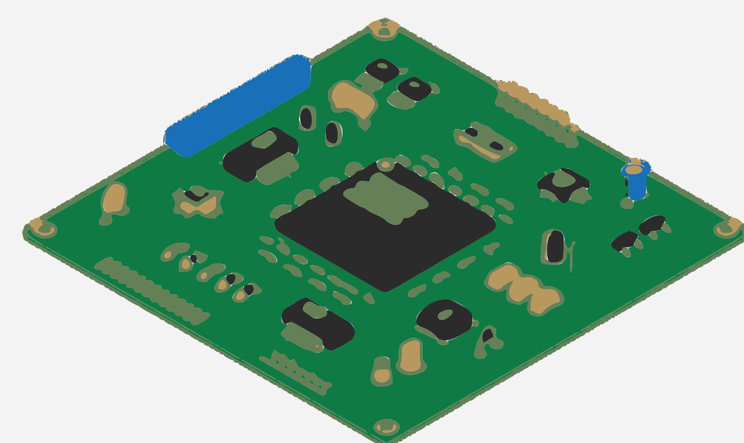
PCB Scope
Rigid, Flexible, Flex-Rigid, HDI, Aluminum, and Semi-Flex PCBs



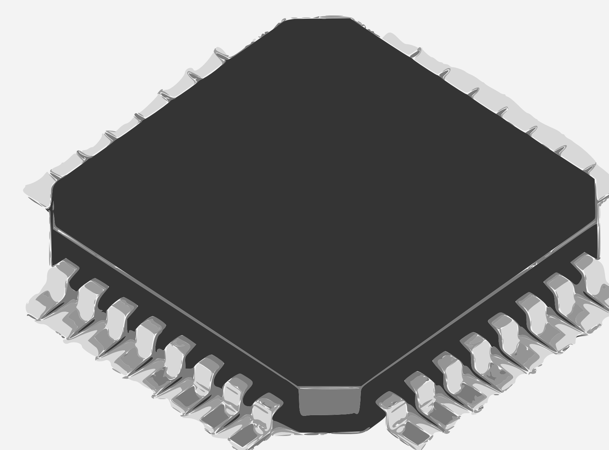
Wire Bonding
Fine Pitch 55um x 65um
High Speed Wire Bonding
6.5 wires/second



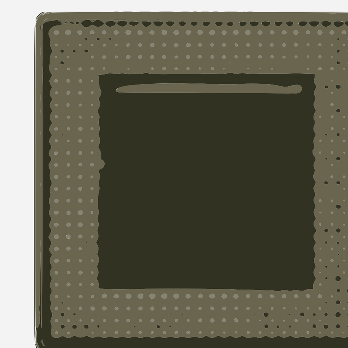
Fine Pitch IC
Minimum 0.2mm pitch



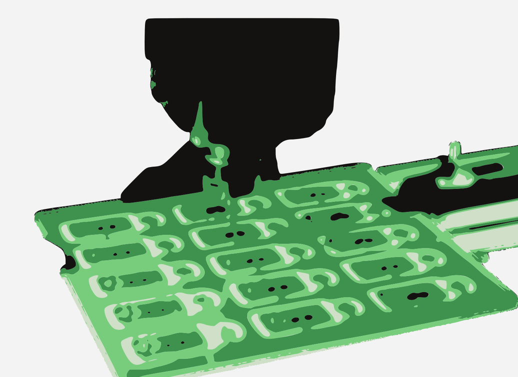
Maximum PCB Size
Standard: 330mm x 250mm
Advanced:410mm x 360mm



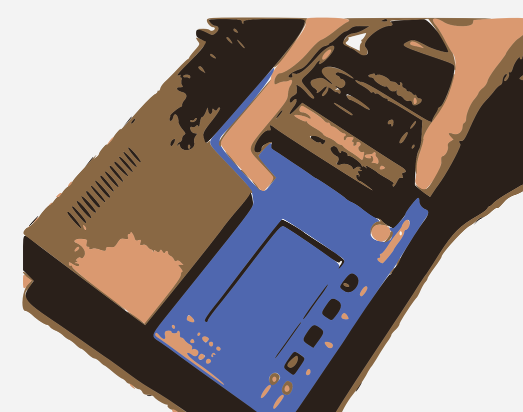
Component Size
From 1005 to 24mm x 72mm



BGA, Micro-BGA, FGBA Flip Chip and CSP
Minimum Ball Pitch 0.2mm
Ball Dimension 0.1mm

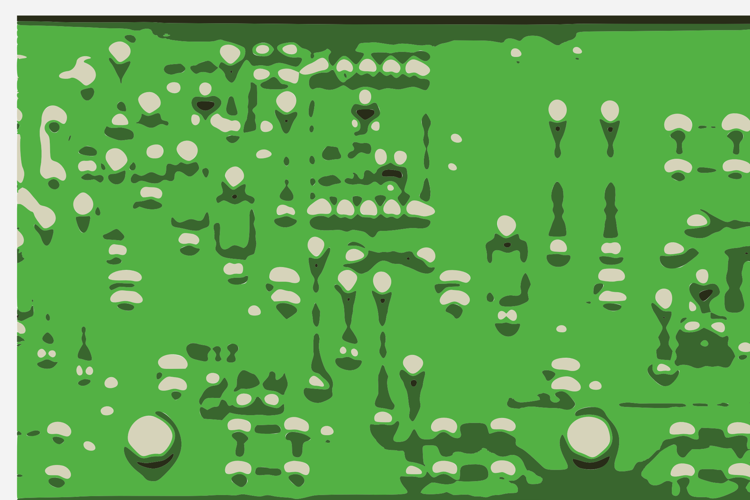


Depanelization
Routing Machine
Scoring Machine

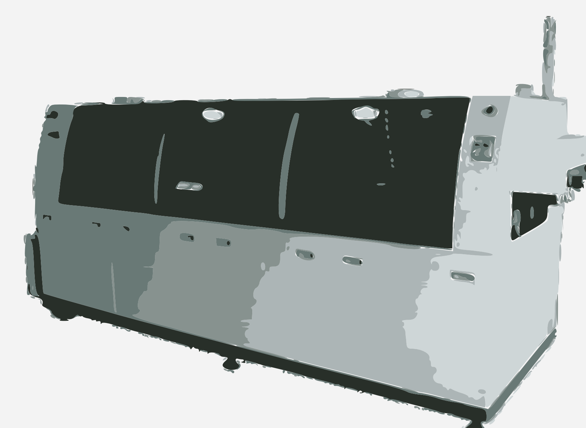


IC Programming (Online/Offline)

Manufacturing Specification
IPC 610 Class 2 & 3



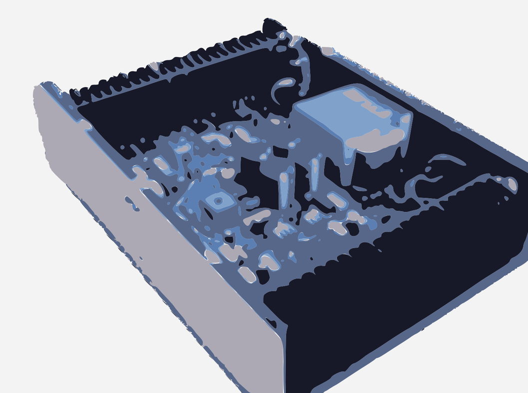
Surface Mount Capacity: 78 Million chips/month



Lead Free Soldering
Surface Mount Reflow, Wave Soldering
Selective Soldering, Robotic Soldering

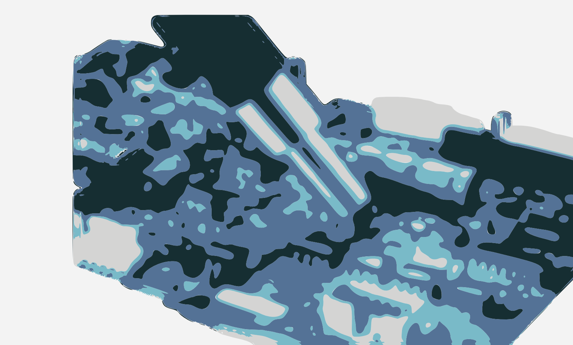
Testing Capability
AOI, ICT, X-Ray, SPI, Burn-In Test
Customized Functional Test

7 Surface Mount Technology Lines

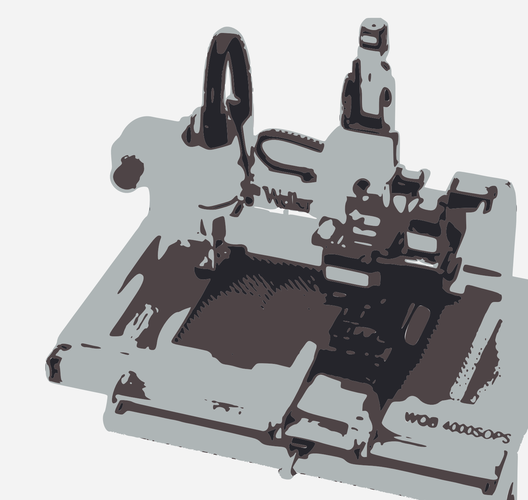


Box Assembly

Cable Harness Assembly



Conformal Coating and Nano Coating



BGA Rework Station

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